


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/25/15833
1.3 Title of PCN	STM32MP15x - product enhancement
1.4 Product Category	STM32MP15x
1.5 Issue date	2025-10-23

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	ST Crolles 300 (France)

4. Description of change

	Old	New
4.1 Description	Current STM32MP15x (Die 500 - cut2.1 - Revision Z) product has limitation : - Improper isolation of protected secure resources - Improper MCU resource isolation as described in Errata Sheet ES0438 - Revision 11 - September 2024.	New STM32MP15x (Die 500 - cut2.2 - Revision Y) product enhancement fixes those limitations: - Improper isolation of protected secure resources - Improper MCU resource isolation as described in Errata Sheet ES0438 - Revision 11.1 - October 2024.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change

5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "Z" to "Y" on Package Marking
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7. Timing / schedule

7.1 Date of qualification results	2024-09-05
7.2 Intended start of delivery	2026-02-17
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	15833 MDG-MCD-RER1902 V3.0 - STM32MP15x - Die 500XXXY - Reliability evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-10-23

9. Attachments (additional documentations)		
15833 Public product.pdf 15833 MDG-MCD-RER1902 V3.0 - STM32MP15x - Die 500XXXY - Reliability evaluation report.pdf 15833 _Additional information.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32MP153AAA3	

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